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Part Number: [0533534071](#)
Status: **Active**
Description: 0.80mm (.031") Pitch Header, Surface Mount, Dual Row, Vertical Stacking, 7.00 and 8.00mm (.276 and .315") Stacking Heights, Lead-free, 40 Circuits

Documents:
[3D Model](#) [Product Specification PS-52465-010 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

General

Product Family	PCB Headers
Series	53353
Application	Board-to-Board
Product Name	N/A

Physical

Breakaway	No
Circuits (Loaded)	40
Circuits (maximum)	40
Durability (mating cycles max)	30
Glow-Wire Compliant	No
Lock to Mating Part	None
Mated Height (in)	0.276 In
Mated Height (mm)	7.00 mm
Material - Metal	Phosphor Bronze
Material - Plating Mating	Tin
Material - Plating Termination	Tin
Number of Rows	2
Orientation	Vertical
PCB Locator	No
PCB Retention	None
Packaging Type	Embossed Tape on Reel
Pitch - Mating Interface (in)	0.031 In
Pitch - Mating Interface (mm)	0.80 mm
Polarized to PCB	No
Stackable	No
Temperature Range - Operating	-20°C to +105°C
Termination Interface: Style	Surface Mount

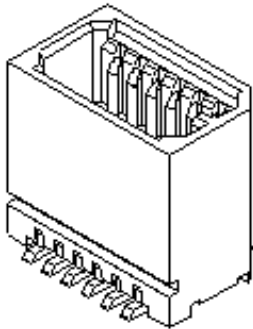
Electrical

Current - Maximum per Contact	0.5A
Voltage - Maximum	50V

Material Info

Reference - Drawing Numbers

Product Specification	PS-52465-010, RPS-52465-042, RPS-52465-044
Sales Drawing	SD-53353-003, SD-53353-004



*Series
image - Reference only*

EU RoHS
ELV and RoHS
Compliant
REACH SVHC
Not Reviewed
Halogen-Free
Status
Not Reviewed

China RoHS



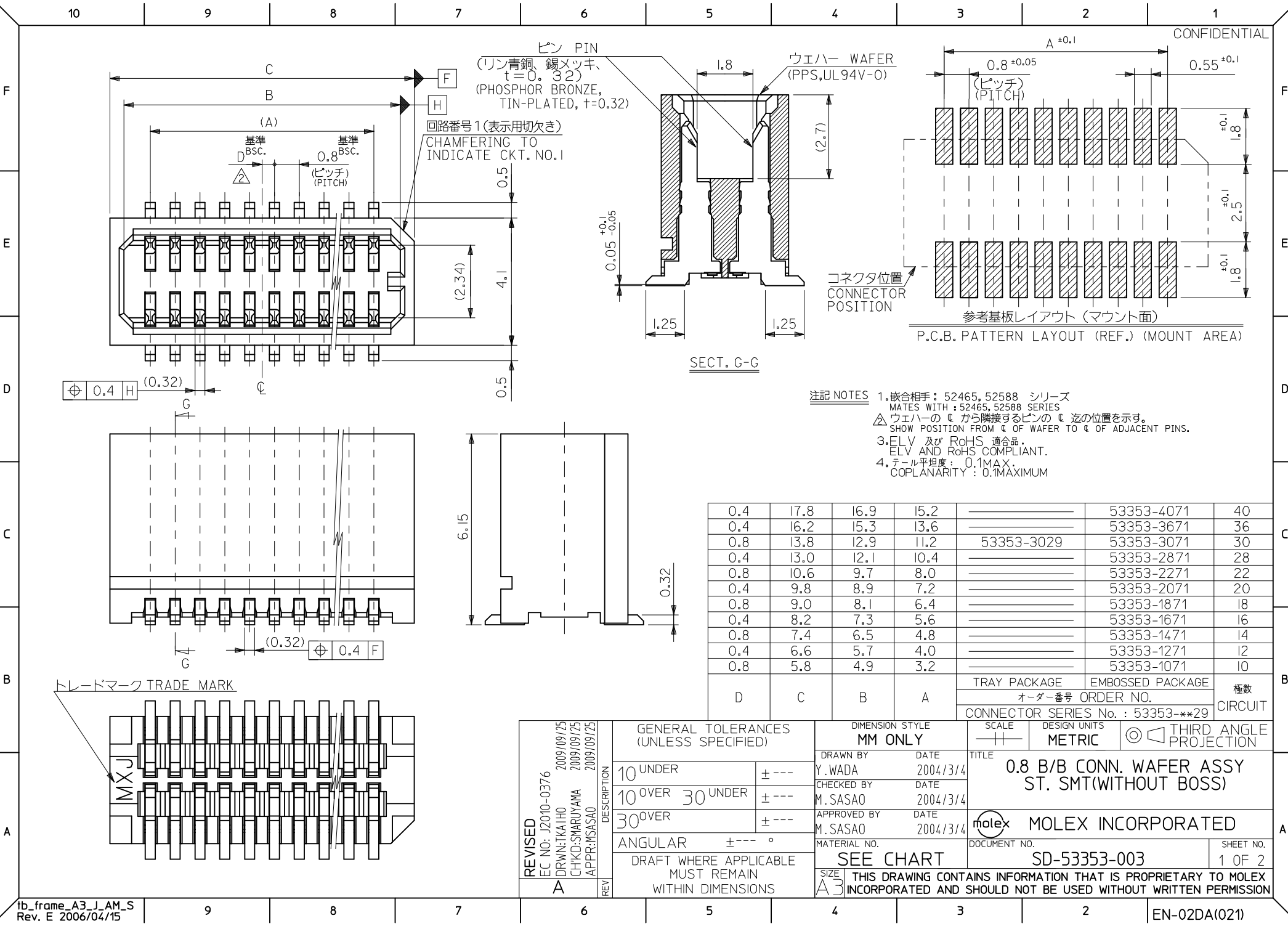
**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
non-product compliance questions.

Search Parts in this Series
[53353Series](#)

Mates With
[52465 PCB Receptacle](#)



ピン PIN
(リン青銅、錫メッキ、
t=0.32)
(PHOSPHOR BRONZE,
TIN-PLATED, t=0.32)

ウェハー WAFER
(PPS,UL94V-0)

回路番号 1 (表示用切欠き)
CHAMFERING TO
INDICATE CKT. NO.1

コネクタ位置
CONNECTOR
POSITION

参考基板レイアウト (マウント面)
P.C.B. PATTERN LAYOUT (REF.) (MOUNT AREA)

SECT. G-G

- 注記 NOTES
1. 嵌合相手: 52465, 52588 シリーズ
MATES WITH: 52465, 52588 SERIES
 2. ウェハーの ϕ から隣接するピンの ϕ 迄の位置を示す。
SHOW POSITION FROM ϕ OF WAFER TO ϕ OF ADJACENT PINS.
 3. ELV 及び RoHS 適合品。
ELV AND ROHS COMPLIANT.
 4. テール平坦度: 0.1MAX.
COPLANARITY: 0.1MAXIMUM

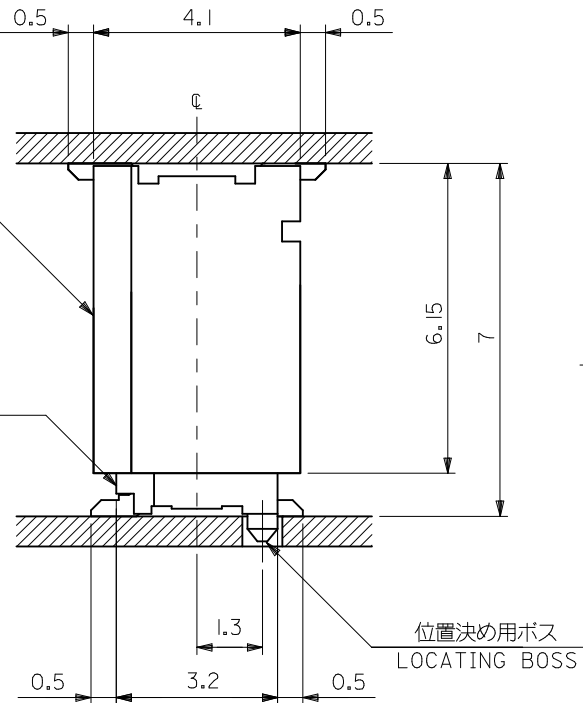
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0.4	16.2	15.3	13.6		53353-3671	36
0.8	13.8	12.9	11.2	53353-3029	53353-3071	30
0.4	13.0	12.1	10.4		53353-2871	28
0.8	10.6	9.7	8.0		53353-2271	22
0.4	9.8	8.9	7.2		53353-2071	20
0.8	9.0	8.1	6.4		53353-1871	18
0.4	8.2	7.3	5.6		53353-1671	16
0.8	7.4	6.5	4.8		53353-1471	14
0.4	6.6	5.7	4.0		53353-1271	12
0.8	5.8	4.9	3.2		53353-1071	10

D	C	B	A	TRAY PACKAGE	EMBOSSED PACKAGE	極数
				オーダー番号	ORDER NO.	
				CONNECTOR SERIES No. : 53353-**-29		CIRCUIT

REVISED EC NO: J2010-0376 DRWN:TKA IHO CHKD:SMARUYAMA APPR:MSASAO A	DESCRIPTION 2009/09/25 2009/09/25 2009/09/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY Y. WADA	DATE 2004/3/4	TITLE 0.8 B/B CONN. WAFER ASSY ST. SMT(WITHOUT BOSS)				
		10 OVER 30 UNDER	± ---	CHECKED BY M. SASAO	DATE 2004/3/4					
		30 OVER	± ---	APPROVED BY M. SASAO	DATE 2004/3/4					
		ANGULAR ± --- °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-53353-003				1 OF 2
		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

53353-***29 (位置決め用ボス無)
(WITHOUT LOCATING BOSS)

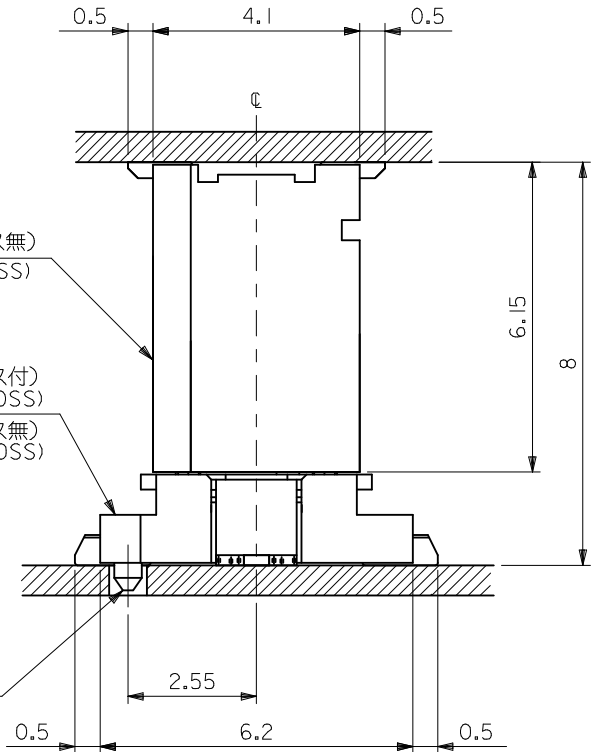
嵌合相手 MATES WITH
52465-***19 (位置決め用ボス付)
(WITH LOCATING BOSS)
52465-***29 (位置決め用ボス無)
(WITHOUT LOCATING BOSS)



53353-***29 (位置決め用ボス無)
(WITHOUT LOCATING BOSS)

嵌合相手 MATES WITH
52588-**** (位置決め用ボス付)
(WITH LOCATING BOSS)
52588-**** (位置決め用ボス無)
(WITHOUT LOCATING BOSS)

位置決め用ボス
LOCATING BOSS



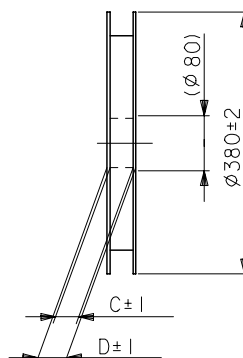
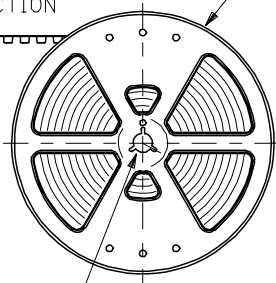
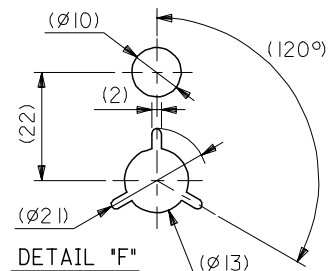
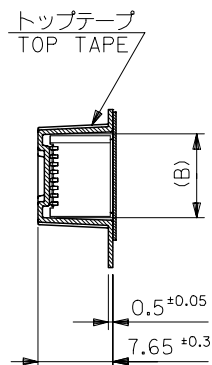
嵌合状態図 (参考)
MATED DRAWING (REF.)

REVISED EC NO.: J2010-0376 DRWN:TKA IHO CHKD:SMRUYAMA APPR:MSASAO 2009/09/25 2009/09/25 2009/09/25	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ++	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY Y.WADA	DATE 2004/3/4	TITLE 0.8 B/B CONN. WAFER ASSY ST. SMT(WITHOUT BOSS)			
		10 OVER 30 UNDER	± ---	CHECKED BY M.SASAO	DATE 2004/3/4				
		30 OVER	± ---	APPROVED BY M.SASAO	DATE 2004/3/4	 MOLEX INCORPORATED			
		ANGULAR ± --- °		MATERIAL NO.					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-53353-003		2 OF 2	
	A		SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

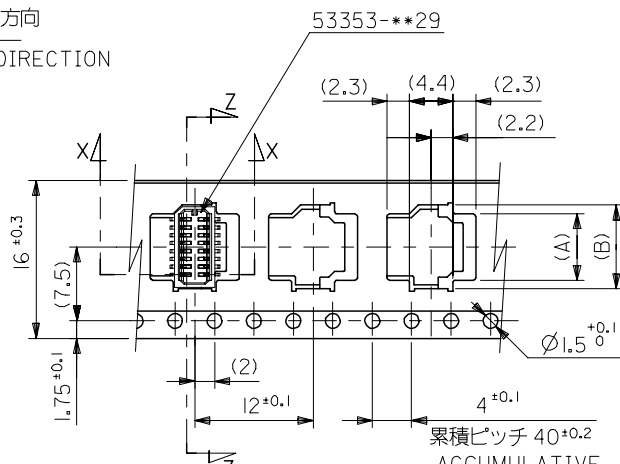
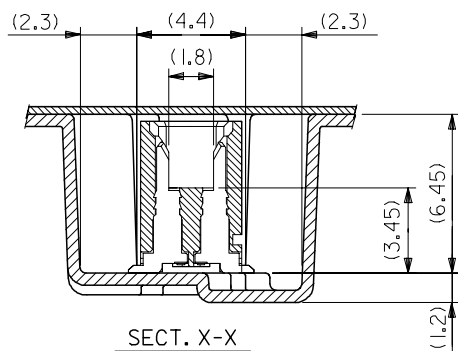
10 9 8 7 6 5 4 3 2 1

引き出し方向
PULL OUT DIRECTION

REEL

引き出し方向
PULL OUT DIRECTION

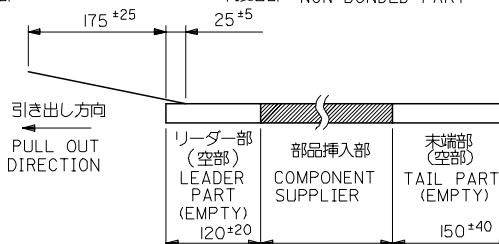
SECT. Z-Z

累積ピッチ 40±0.2
ACCUMULATIVE
PITCH 40±0.216mm幅キャリアテープ
16mm WIDTH CARRIER TAPESECT. X-X
(SCALE:5-1)

注記 NOTES

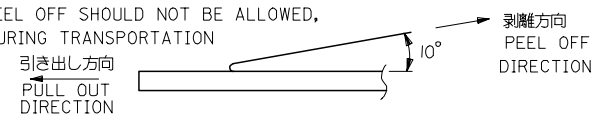
1. 梱包数量: 1000個/リール NUMBER OF CONNECTORS: 1000PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH

トップテープ TOP TAPE
リーダー部 LEADER PART
未接着部 NON-BONDED PART



3. トップテープの剥離強度: (剥離方向は下図参照)
0. 1~1. 3N {10~130gf} 尚、本規格値は、出荷時に適用。
(但し、輸送時に剥離が発生しない事。)

PEELING OFF FORCE OF TOP TAPE
0. 1~1. 3N {10~130gf} (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED,
DURING TRANSPORTATION



4. 材料 MATERIAL
キャリアテープ: ポリプロピレン (PP) CARRIER TAPE: POLYPROPYLENE
トップテープ: PET, PE, PEF TOP TAPE: PET, PE, PEF
リール: ポリスチレン (PS) REEL: POLYSTYRENE (PS)
<リサイクル材を含む> <RECYCLE MATERIAL CONTAINED>

5. 本製品は53353-**-91の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53353-**-91.

16	21.4	17.4	8.5	6.7	53353-1671	16
			7.7	5.9	53353-1471	14
			6.9	5.1	53353-1271	12
			6.1	4.3	53353-1071	10
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

MODEL NO. 53353-**-71
THIRD ANGLE PROJECTION

REVISED EC NO: J2005-2/59 DRAWN: KENSUJUKI CHKD: NUKITA APPR: NUKITA A	DESCRIPTION 2005/01/26 2005/01/26 2005/02/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY YWADA	DATE 2004/03/04	TITLE 0.8 BTB CONN WAFER ASSY ST SMT WITHOUT BOSS EMBTP PKG -LEAD FREE-  MOLEX INCORPORATED			
		10 OVER 30 UNDER	±0.25	CHECKED BY MSASAO	DATE 2004/03/04				
		30 OVER	±0.3	APPROVED BY MSASAO	DATE 2004/03/04				
		ANGULAR ±3°		MATERIAL NO. SEE CHART					DOCUMENT NO. SD-53353-004
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

F

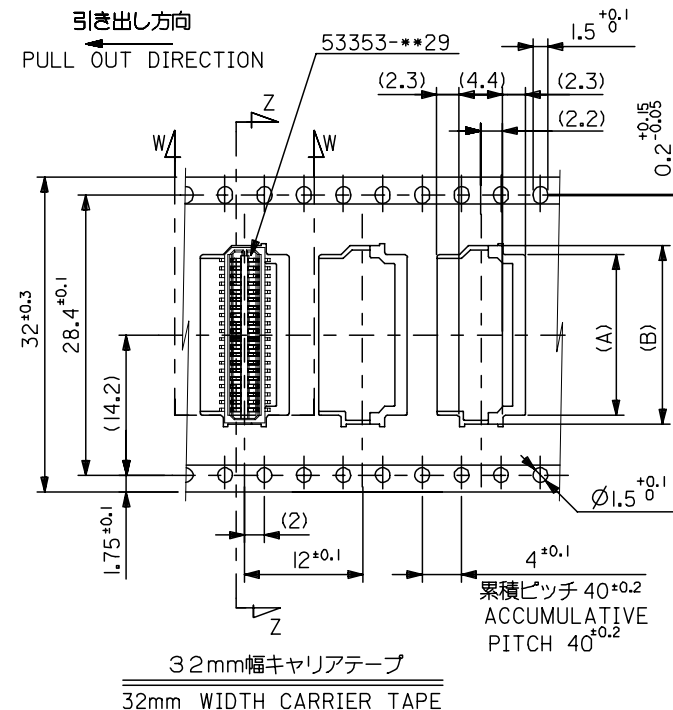
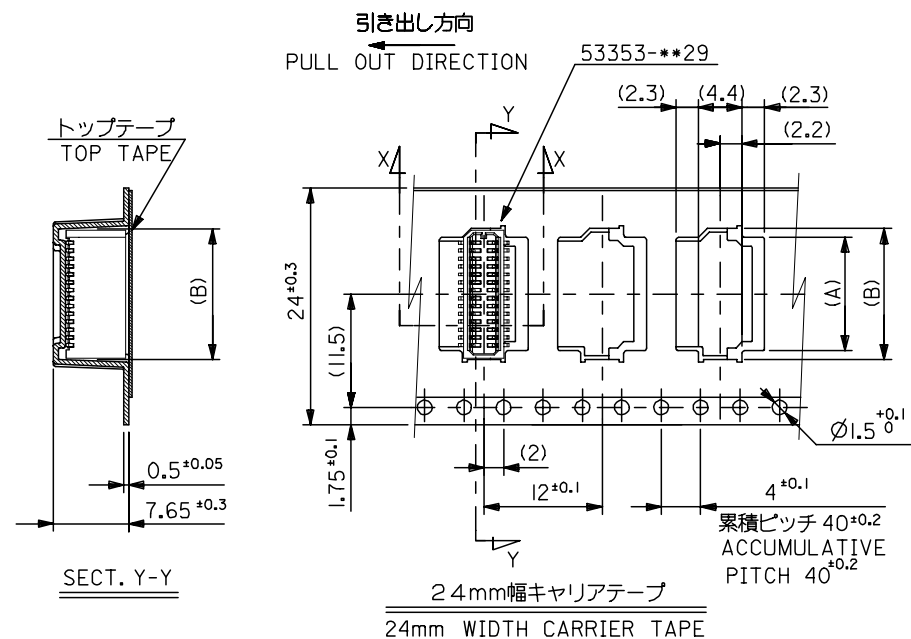
E

D

C

B

A



32	37.4	33.4	18.1	16.3	53353-4071	40
			16.5	14.7	53353-3671	36
24	29.4	25.4	14.1	12.3	53353-3071	30
			13.3	11.5	53353-2871	28
			10.9	9.1	53353-2271	22
			10.1	8.3	53353-2071	20
			9.3	7.5	53353-1871	18
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

MODEL NO. 53353-**-71

REVISED EC NO: J2005-2159 DRAWN:KENSUJUKI CHKD:NUKITA APPR:NUKITA	DESCRIPTION 2005/01/26 2005/01/26 2005/02/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY YWADA	DATE 2004/03/04	TITLE 0.8 BTB CONN WAFER ASSY ST SMT WITHOUT BOSS EMBTP PKG -LEAD FREE- MOLEX INCORPORATED			
		10 OVER 30 UNDER	±0.25	CHECKED BY MSASAO	DATE 2004/03/04				
		30 OVER	±0.3	APPROVED BY MSASAO	DATE 2004/03/04				
		ANGULAR	±3°	MATERIAL NO.	DOCUMENT NO.				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-53353-004			SHEET NO. 2 OF 2
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							